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Docket No.
36080-00800

Applicant: Edward G. Combs *et al.*
Serial No.: 09/902,878
Date Filed: July 11, 2001
Group Art Unit: 2827
For: Enhanced Thermal Dissipation Integrated Circuit Package

I hereby certify that this :

Interview Summary Under 37 C.F.R. § 1.133; Certificate of Mailing; and return receipt postcard.

are being deposited with the United States Postal Service via first class mail in an envelope addressed to: Mail Stop AF, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

January 30, 2003

Sandina M. Marino

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Signature of Person Mailing Correspondence

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 09/902,878
Applicant(s) : Edward G. Combs *et al.*
Filed : July 11, 2001
TC/A.U. : 2827
Examiner : Alonzo Chambliss
Docket No. : 36080-00800
Customer No. : 27171
Title : *Enhanced Thermal Dissipation Integrated Circuit Package*

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COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria, VA 22313-1450

INTERVIEW SUMMARY UNDER 37 C.F.R. § 1.133

Sir:

This Interview Summary is being submitted to provide Applicants' complete written statement of the reasons – presented at the November 11, 2003 telephonic interview with Examiner Chambliss – why favorable action was warranted in this application.

As an initial matter, Applicants thank Examiner Chambliss for participating in the November 11 interview.

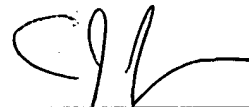
Examiner Chambliss and the undersigned attorney of record in this application participated in the interview. A draft document containing proposed but non-entered claims was discussed. Applicants provided this document to the Examiner on November 11, 2003 prior to the interview, and it is attached hereto as Exhibit A. Primarily, independent claim 3 and U.S. Patent No. 5,175,612 to Long were discussed.

During the interview, the undersigned attorney of record argued that the Long reference did not disclose or suggest an integrated circuit package having, among other things, a

heat sink comprising an extending finger when viewed from a top of the package. The Examiner agreed. Applicants respectfully note, however, that other features of the claims in the present application are also significant.

Applicants submit that no fee is necessary in connection with this paper. However, in the event the Commissioner determines that an additional fee is due for this paper, the undersigned hereby authorizes the Commissioner to charge any fees required therefor to Milbank's deposit account no. 13-3250, order no. 36080-00800. A DUPLICATE COPY OF THIS PAGE IS ENCLOSED HEREWITH.

Respectfully submitted,
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January 30, 2004

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